Product / Package Information

Package	LP2E- GaAs
Body Size	
Lead Count	
Terminal Finish	100Sn
MS Number	

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.64 E-03	86.20	862000	43.00	430002
Thermosets	Epoxy resin	Proprietary	3.23 E-04	6.00	60000	2.99	29931
Thermosets	Phenol Resin	Proprietary	3.23 E-04	6.00	60000	2.99	29931
Other inorganic materials	Metal Hydroxide	Proprietary	8.08 E-05	1.50	15000	0.75	7483
Other inorganic materials	Carbon Black	1333-86-4	1.62 E-05	0.30	3000	0.15	1497
Subtotal			5.38 E-03	100.00	1000000	49.88	498842

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.60 E-03	97.50	975000	42.58	425761
Copper & its alloys	Iron	7439-89-6	1.11 E-04	2.35	23500	1.03	10262
Copper & its alloys	Zinc	7440-66-6	5.66 E-06	0.12	1200	0.05	524
Copper & its alloys	Phosphorus	7723-14-0	1.41 E-06	0.03	300	0.01	131
Subtotal			4.71 E-03	100.00	1000000	43.67	436678

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.20 E-04	100.00	1000000	2.04	20382

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.10 E-04	99.99	1000000	1.01	10145

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	1.74 E-04	100.0	1000000	1.61	16120

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.35 E-04	70.00	700000	1.25	12484
Other organic materials	Epoxy Resin	9003-36-5 / 30583-72-3	3.85 E-05	20.00	200000	0.36	3567
Other organic materials	t-butyl phenyl glycidyl ether	3101-60-8	1.44 E-05	7.50	75000	0.13	1338
Other organic materials	Phenolic hardener	92-88-6	2.89 E-06	1.50	15000	0.03	268
Other organic materials	Butyl cellosolve acetate	112-07-2	1.93 E-06	1.00	10000	0.02	178
Subtotal			1.93 E-04	100.0	1000000	1.78	17834

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.08 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

Product / Package Information

Package	LP2
Body Size	
Lead Count	
Terminal Finish	SnPb
MS Number	

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.78 E-03	87.23	872326	44.11	441129
Thermosets	Phenol Resin	Proprietary	2.13 E-04	3.89	38893	1.97	19668
Thermosets	Epoxy resin	Proprietary	4.11 E-04	7.49	74938	3.79	37896
Thermosets	Brominated Epoxy Resin	40039-93-8	2.69 E-05	0.49	4911	0.25	2484
Other inorganic materials	Antimony Trioxide	1309-64-4	3.08 E-05	0.56	5617	0.28	2841
Other inorganic materials	Carbon Black	1333-86-4	1.82 E-05	0.33	3313	0.17	1676
Subtotal			5.49 E-03	100.00	1000000	50.57	505693

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.60 E-03	97.50	975000	42.37	423700
Copper & its alloys	Iron	7439-89-6	1.11 E-04	2.35	23500	1.02	10212
Copper & its alloys	Zinc	7440-66-6	5.66 E-06	0.12	1200	0.05	521
Copper & its alloys	Phosphorus	7723-14-0	1.41 E-06	0.03	300	0.01	130
Subtotal			4.71 E-03	100.00	1000000	43.46	434564

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.46 E-04	85.0	850000	1.35	13479
Tin & its alloys	Lead	7439-92-1	2.58 E-05	15.0	150000	0.24	2379
Subtotal			1.72 E-04	100.0	1000000	1.59	15858

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.10 E-04	99.99	1000000	1.01	10095

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	1.74 E-04	100.0	1000000	1.60	16042

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.35 E-04	70.00	700000	1.24	12423
Other organic materials	Epoxy Resin	9003-36-5 / 30583-72-3	3.85 E-05	20.00	200000	0.35	3550
Other organic materials	t-butyl phenyl glycidyl ether	3101-60-8	1.44 E-05	7.50	75000	0.13	1331
Other organic materials	Phenolic hardener	92-88-6	2.89 E-06	1.50	15000	0.03	266
Other organic materials	Butyl cellosolve acetate	112-07-2	1.93 E-06	1.00	10000	0.02	177
Subtotal			1.93 E-04	100.0	1000000	1.77	17748

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.08 E-02**	**100.00**	**1000000**

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